

## AMENDMENTS TO THE CLAIMS

1. (Currently amended) A cooling apparatus for a computer comprising:
  - a conductive base plate configured to be installed over a CPU and to transfer heat therefrom;
  - a heat conductor thermally coupled to the base plate adapted to carry heat transferred to the base plate by the CPU away from the base plate;
  - a heat sink thermally coupled to the heat conductor for dissipating heat carried by the heat conductor;
  - a fan for dispersing heat transferred to the heat sink, wherein the fan is configured to direct an airflow over a power supply installed within the computer to remove heat therefrom; and
  - a housing for the heat sink and the fan configured to be installed adjacent to a window in a computer chassis such that the fan can direct airflow through the heat sink and out the window.
2. (Original) The apparatus of claim 1, wherein the computer chassis is for a small form factor computer.
3. (Original) The apparatus of claim 1, wherein the heat conductor comprises one or more heat pipes.
4. (Original) The apparatus of claim 3, wherein the thermal conductor comprises a plurality of heat pipes, each heat pipe connected to the heat sink through a hole to facilitate heat exchange therebetween.
5. (Original) The apparatus of claim 3, wherein the heat pipes contain at least one of: a metal mesh grid and a liquid for transferring the heat contained within the heat pipe.
6. (Canceled)

7. (Original) The apparatus of claim 1, wherein the fan is configured to face the power supply.
8. (Previously presented) The apparatus of claim 1, wherein the heat sink comprises a plurality of cooling fins.
9. (Previously presented) The apparatus of claim 8, wherein the cooling fins are made of one of: copper and compression molded aluminum.
10. (Original) The apparatus of claim 1, further comprising a computer chassis comprising the window in the computer chassis, a screen over the window, and a second window configured to intake ambient air.
11. (Previously presented) A method of cooling the interior of a computer chassis, the method comprising:  
transferring heat generated by a CPU in the computer chassis to a heat sink through a base member installed adjacent to the CPU and a cooling pipe connected to the heat sink; and  
drawing ambient airflow into the chassis through a first window in the chassis, wherein the air flow is directed to pass over a power supply in the chassis, pass through a fan, and be blown by the fan over the heat sink to outside the chassis.
12. (Canceled)